

Thermal Test Report

Model : YY-0221

Thermal Performance Contest

Date:Dec.16, 2004

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1. Introduction

The purpose of this evaluation is to find the best performance thermal solution by system operated as for Intel P4 3.4G processor .

2. References

ATX spec <http://formfactors.org>

3. Thermal Test

3.1 Test Configuration

Chassis	YY-0221
Power Supply	Delta GPS-350CN-100A,350W
Chassis Fan	TOP DF1208BM, Quantity:1 Speed:2500RPM (Middle Speed) TOP DF1209BB, Quantity:1 Speed:2600RPM (Middle Speed) <i>System config. To be tested with various modes, please refer to table 4.1 & 4.2</i>
Processor	Intel P4 Prescott 3.4GHz/800MHz 1MB L2-Cache LGA-775, Quantity:1
Processor Thermal solution	Intel Boxed Cooler
Motherboard	ASUS P5GD1-VM(intel 915G)
Memory	Kingston DDR400 512MB, Quantity: 2
Hard Drive	SEAGATE ST380013AS 80G, Quantity: 1
CD ROM	Cyber CD526D 52X, Quantity: 1
Floppy Drive	Mitsumi D359M3, Quantity: 1
AGP Card	GIGABYTE GA-V-NX53128T, Quantity: 1
PCI-Lan Card	D-LINK DFE-530TX, Quantity: 1
PCI-Sound Card	ESS SC1938, Quantity: 1

3.2 Test Equipment Used

FULL SYSTEM OPERATION

Fluke Hydra 2635A

Software: Intel P4 Prescott MAXPOWER Rev:1.4.2

3.3 Test Process

The peripherals listed in section 1 were installed in the chassis and thermocouples were attached at the points designated in section 4. The chassis was tested in a controlled temperature held at a constant 35°C. The thermal readings communicated from the sensors on the test board to the test software. The system was exercised until the initial thermal gradient reached a consistent level with a slope-nearing zero. During testing, the ambient temperature was monitored approximately 2" from the front bezel of the chassis.

3.4 Data Recorded

Temperature readings are measured at the following location(s):

- Ambient -- Hotbox ambient temperature (2" from the front center of the chassis)

- Tinlet1 – Internal ambient temperature of the processor heatsink .5” away from the center of fan hub (near the rear port)
- Tinlet2 – Internal ambient temperature of the processor heatsink .5” away from the center of fan hub (near the PSU)
- Tinlet3 – Internal ambient temperature of the processor heatsink .5” away from the center of fan hub (near the DIMM slot)
- Tinlet4 – Internal ambient temperature of the processor heatsink .5” away from the center of fan hub (near the chipset)
- Tcase -- Processor case temperature

4. Test Result (see table 4.1), & Test mode details (Table 4.2)

Summary: PASS

*According to the FMB guidance, the CPU is FMB04B, TDP=115W
Psc Tc= Px0.25+44.0 =72.75 °C (Tc spec)*

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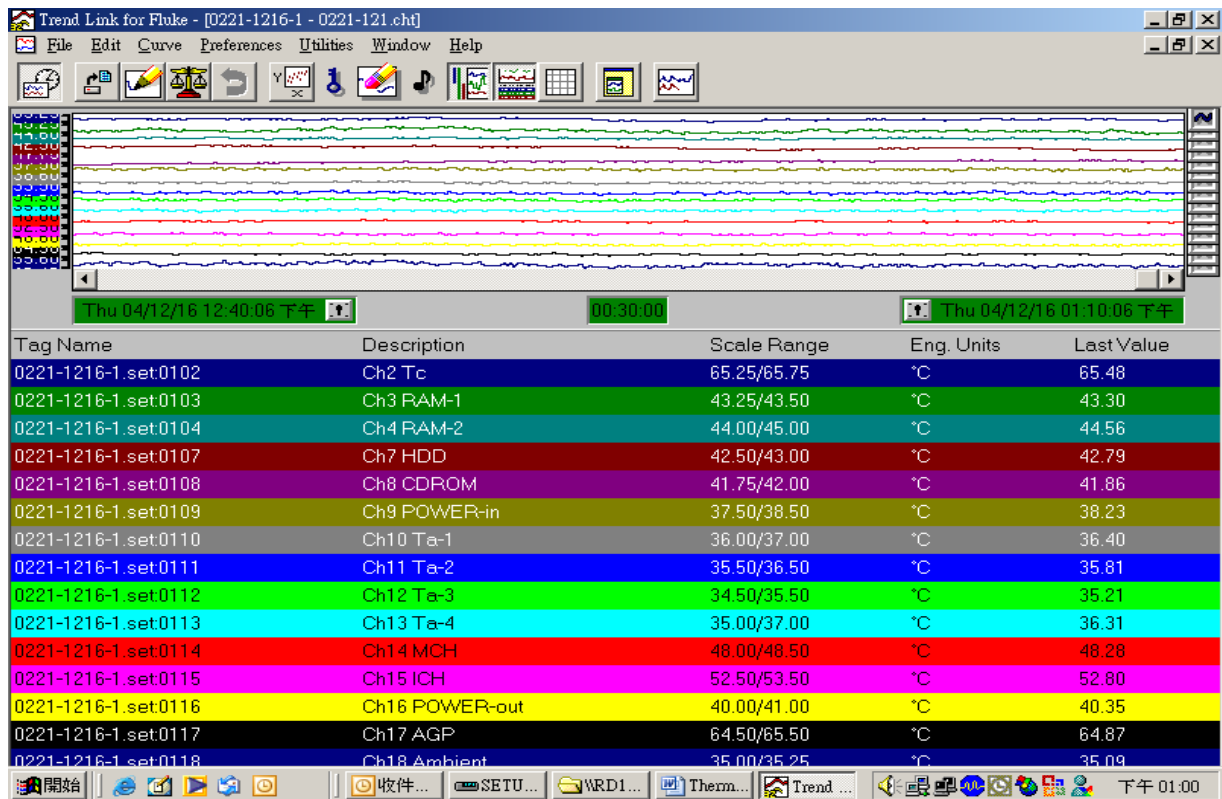
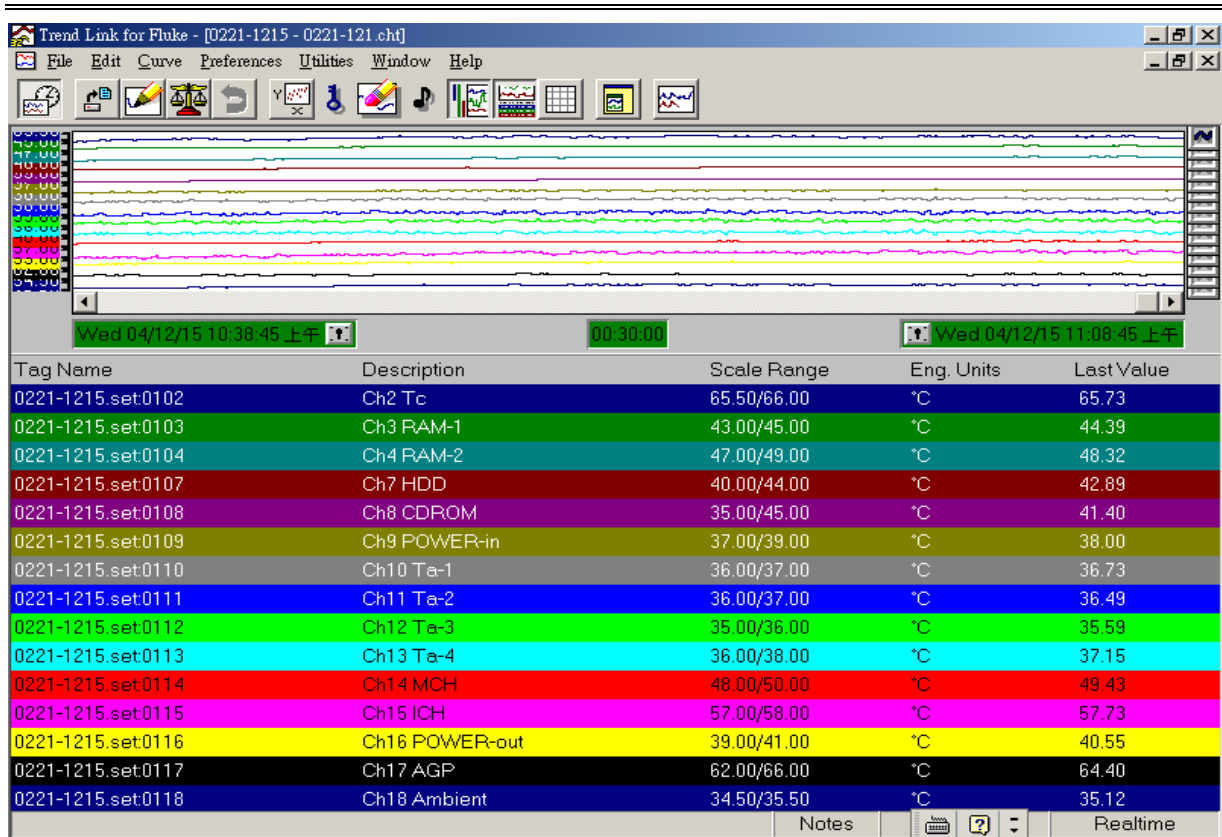
Table 4.1
Date: Dec.15.2004

Mode Introductions	Mode 1	Mode 2	Mode 3	Mode 4
Power Model	Delta 350CN-100A (with 8cm Fan for airflow out, vents for air flow out)			
System Fan- 12 cm *1 Mounted in front side of chassis	No	Yes-Low speed Airflow in	No	Yes-Low speed Airflow out
System Fan- 8 cm *1 (Mounted in Rear side of chassis)	Yes- Middle speed	Yes- Middle speed	No	No
System Fan- 9 cm *1 (Mounted in Side of chassis)	No	No	No	No
Airguide-CAG 1.1	Yes	Yes	Yes	Yes
Run the test under the software on 100% level	100%	100%	100%	100%
Test Result (values was according to the screens of Fluke monitor)				
DIMM-1	44.4	43.3	49.4	47.8
DIMM-2	48.3	44.6	53.9	51.3
HDD	42.9	42.8	46	44.4
CD ROM	41.4	41.9	45.5	43.6
MCH	49.4	48.3	54.3	52.3
ICH	57.7	52.8	63.6	60.6
AGP Card	64.4	64.9	77.9	73.5
POWER-in	38	38.2	40.8	39.1
POWER-out	40.6	40.4	42.5	41.5
T-inlet 1	36.7	36.4	38.6	37.3
T-inlet 2	36.5	35.8	37.8	36.4
T-inlet 3	35.6	35.2	35.8	35.3
T-inlet 4	37.2	36.3	41.9	38.2
T-inlets average Tambient(1~4)	<u>36.5</u>	<u>35.9</u>	<u>38.5</u>	<u>36.8</u>
T-case	<u>65.7</u>	<u>65.5</u>	<u>68.3</u>	<u>67.3</u>
Ambient(case outside)	35.1	35.1	35.1	35

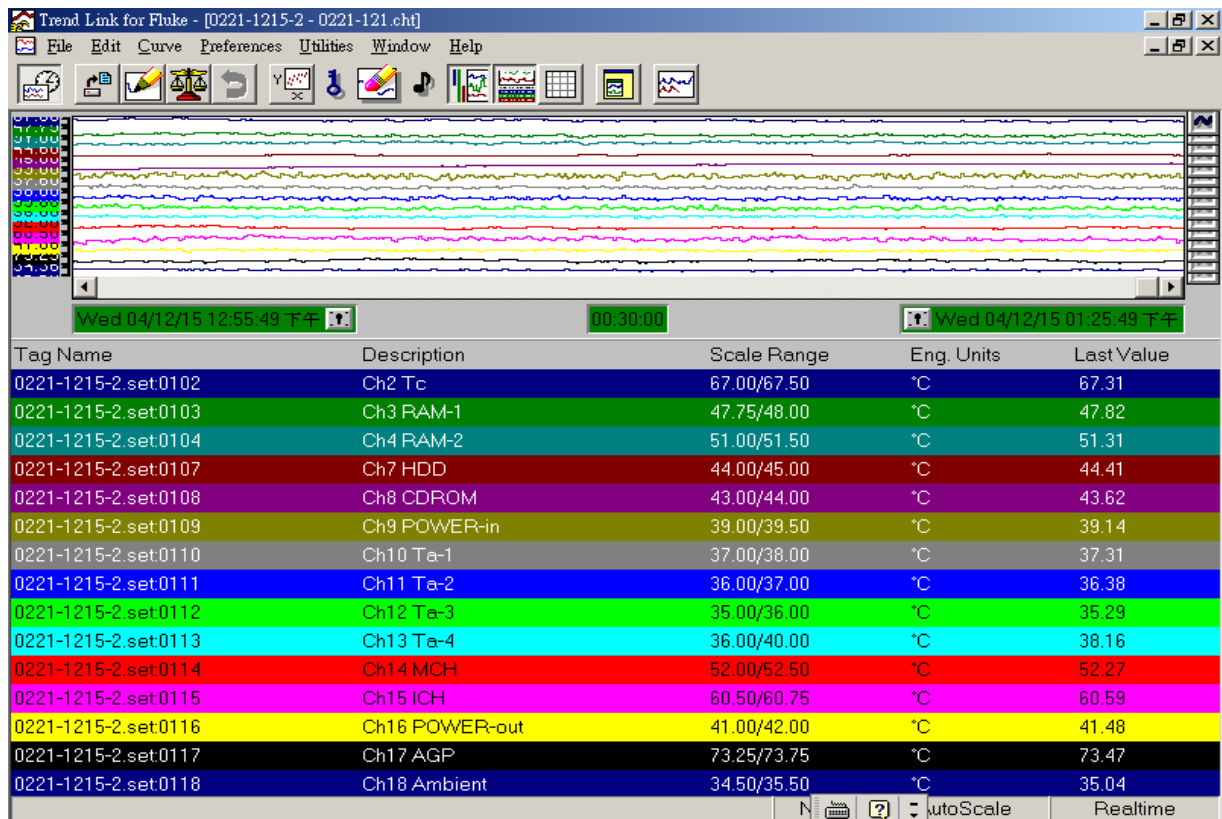
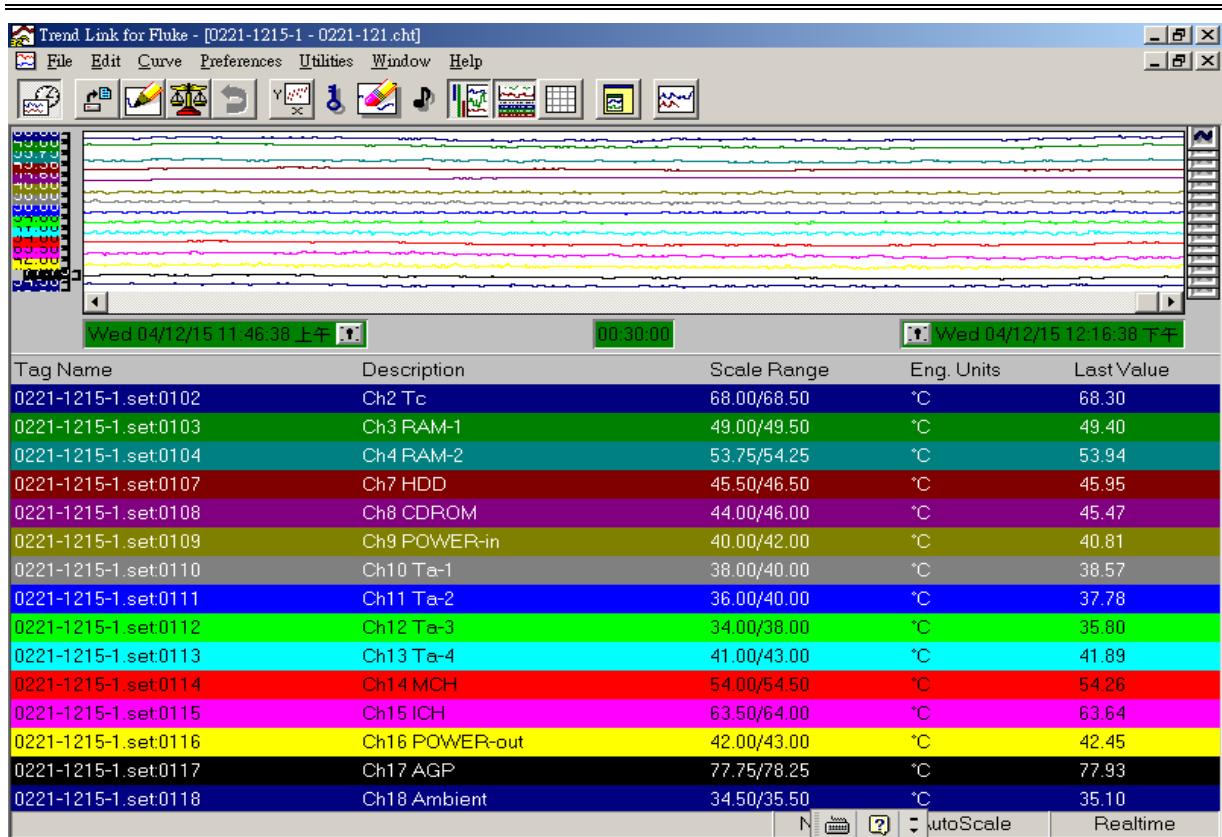
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Mode Introductions	Mode 5	Mode 6	Mode 7	Mode 8
Power Model	Delta 350CN-100A (with 8cm Fan for airflow out, vents for air flow out)			
System Fan- 12 cm *1 Mounted in front side of chassis	No	No	Yes-Low speed Airflow out	Yes-Low speed Airflow in
System Fan- 8 cm *1 (Mounted in Rear side of chassis)	No	No	No	No
System Fan- 9 cm *1 (Mounted in Side of chassis)	No-Vents only	Yes	No-Vents only	No-Vents only
Airguide-CAG 1.1	No	No	No	No
Run the test under the software on 100% level	100%	100%	100%	100%
Test Result (values was according to the screens of Fluke monitor)				
DIMM-1	53.3	44.9	50.3	49.9
DIMM-2	54.4	47.2	52.2	47.2
HDD	46.7	45.1	43.9	46.6
CD ROM	45	43.1	43.7	44.1
MCH	58.6	45.1	54.2	56.2
ICH	65.1	53.2	58.9	56.2
AGP Card	81.6	67.3	77.1	74.1
POWER-in	41.6	40.7	39.7	40.9
POWER-out	42.8	43.3	41.5	42.3
T-inlet 1	50.1	36.3	45.7	48.1
T-inlet 2	50	35.4	43.9	48.9
T-inlet 3	48	35.6	43.7	45.3
T-inlet 4	48.6	36	41.6	45.2
T-inlets average Tambient(1~4)	<u>49.2</u>	<u>35.8</u>	<u>43.7</u>	<u>46.9</u>
T-case	<u>72.3</u>	<u>64.8</u>	<u>69.5</u>	<u>71.2</u>
Ambient(case outside)	35.1	35.1	35	35.1

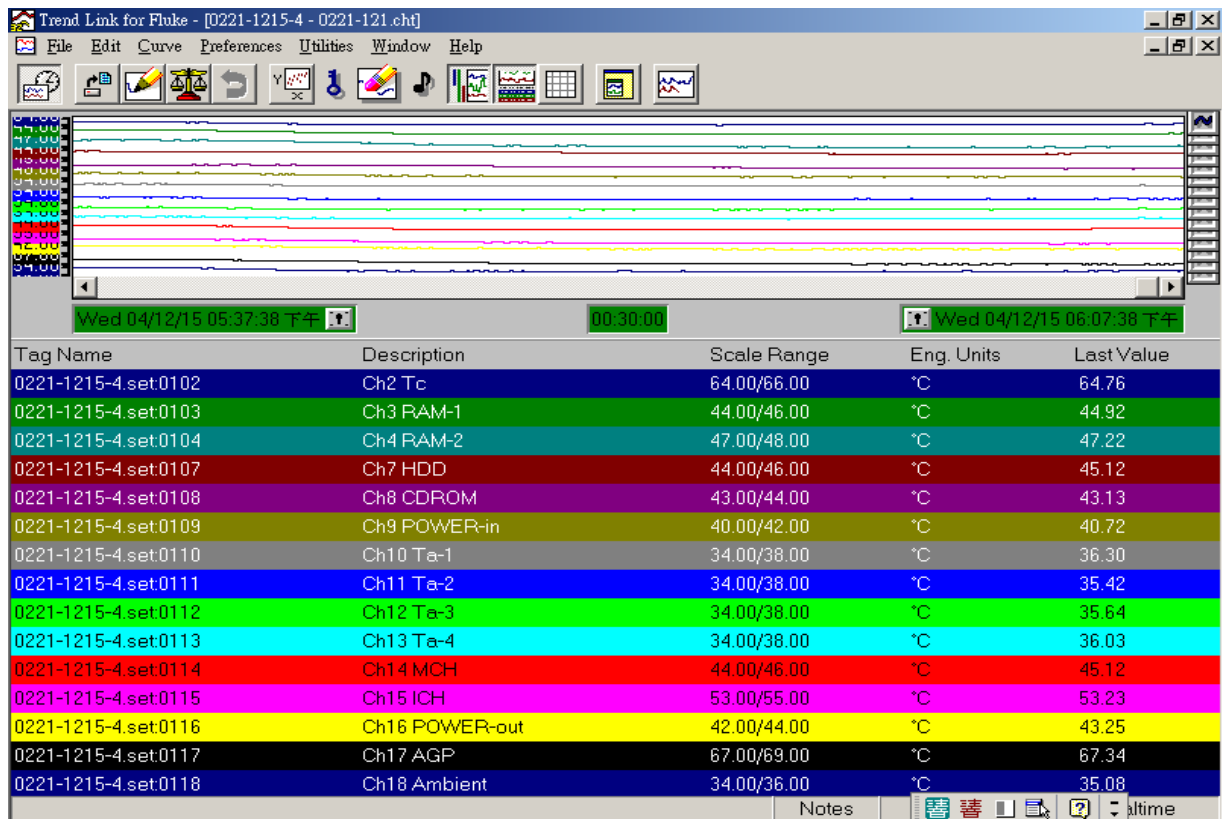
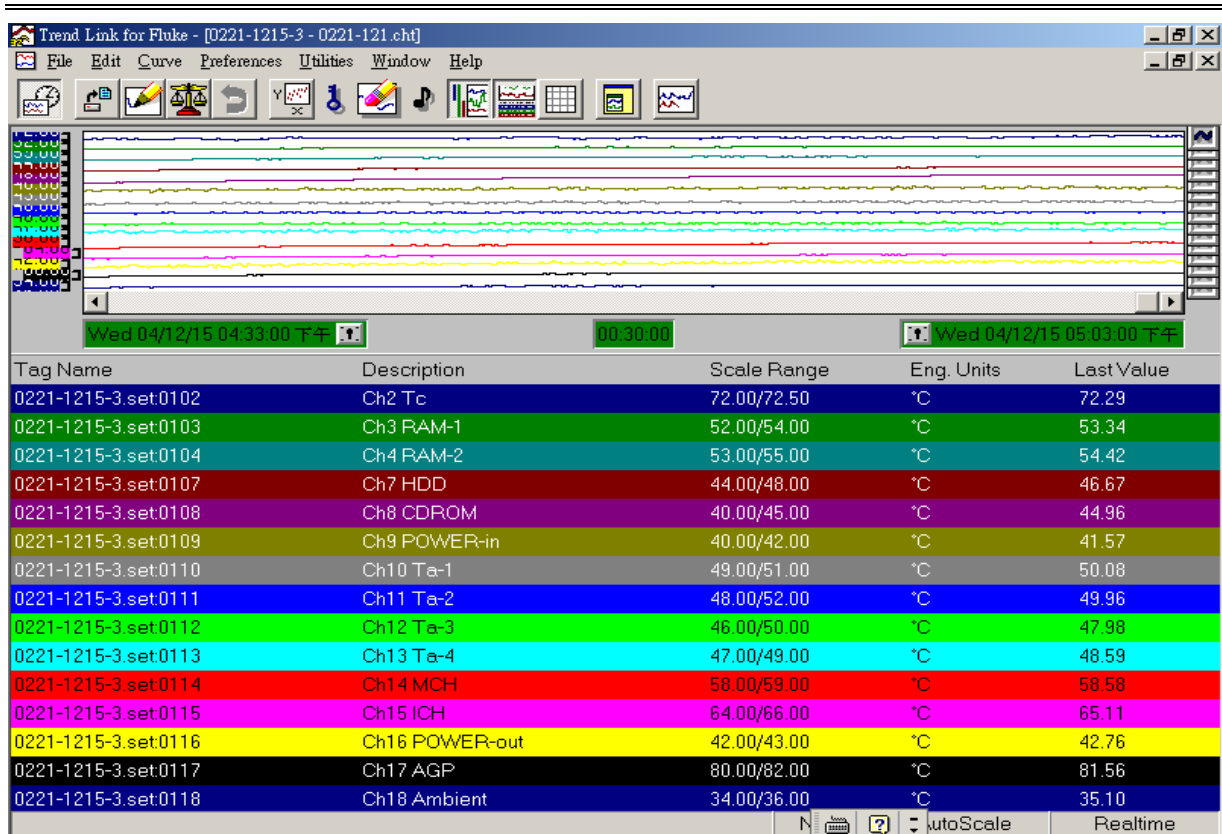
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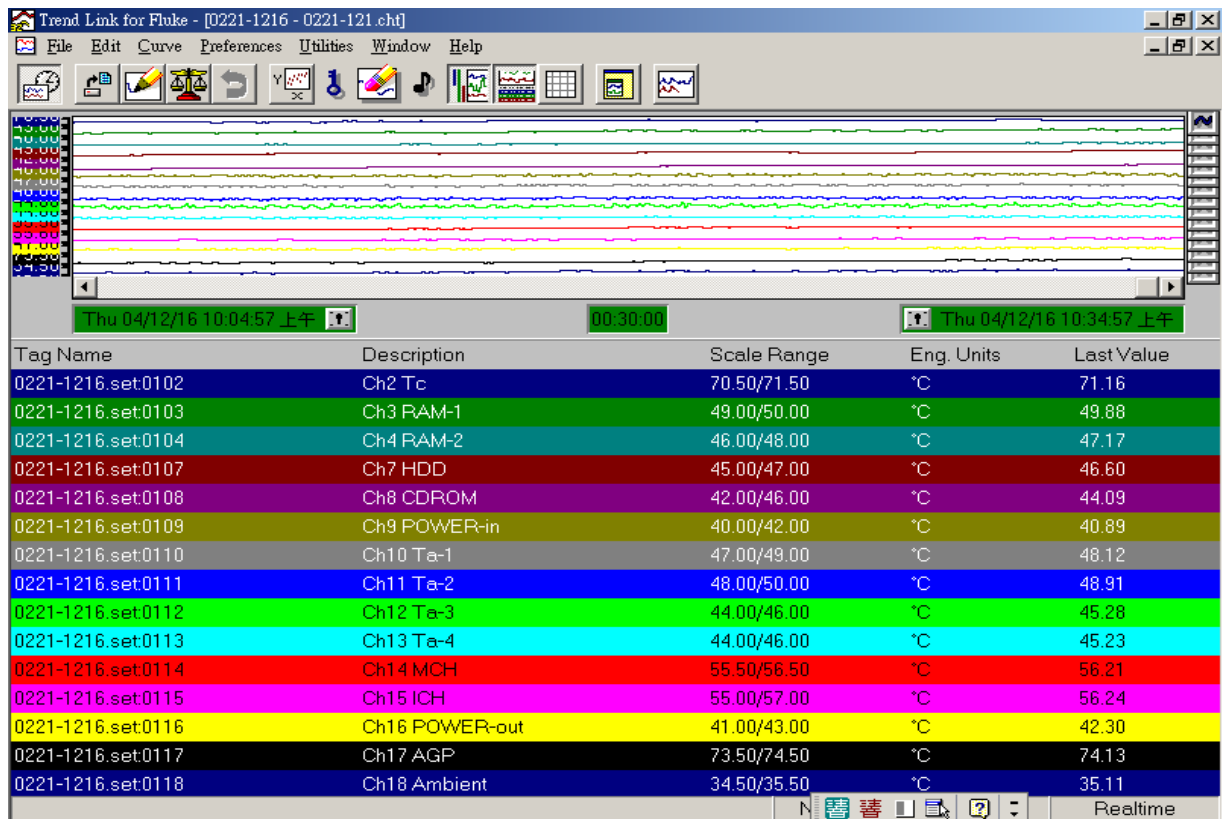
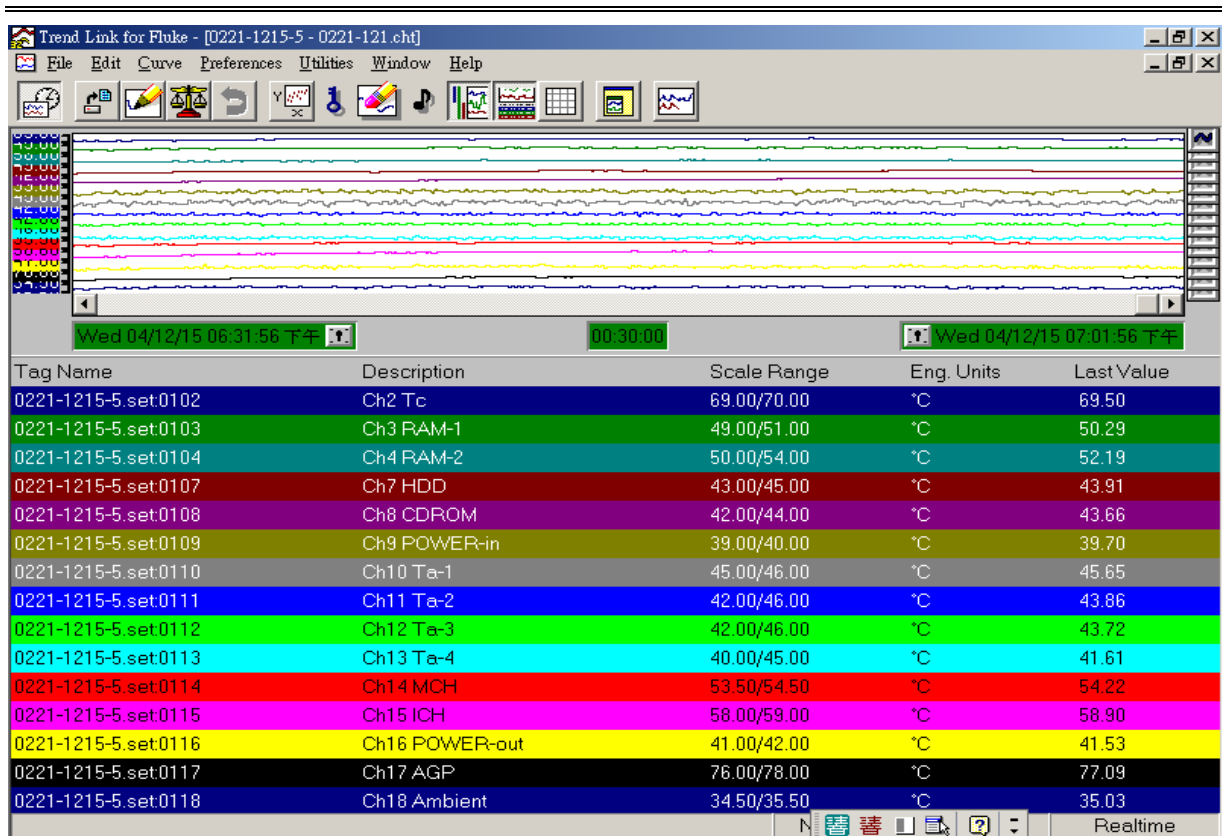
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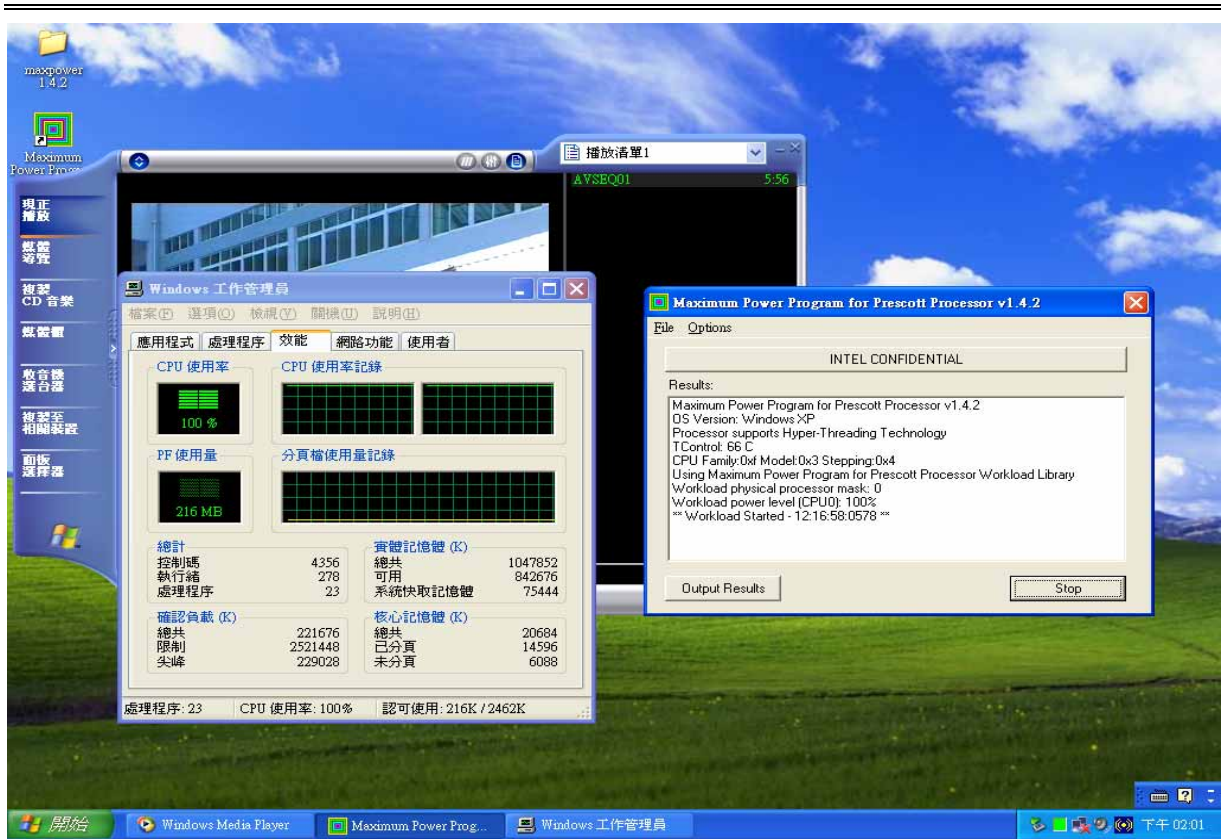


Table 4.2



The view of the chassis front side-1.



The view of chassis front side-2 side.



The view of the chassis right side.



The view of the chassis left side.



The view of the chassis back side.



The view of the thermocouples connections.



The view of system setup (HDD, CDROM, FDD, POWER).



The view of CAG1.1.